

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
-20V	23mΩ@-4.5V	-10A
	26mΩ@-2.5V	
	34mΩ@-1.8V	

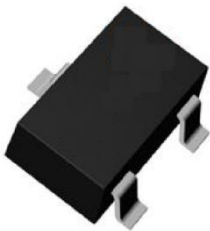
Feature

- Trench Power MV MOSFET technology
- High density cell design for Low $R_{DS(ON)}$
- High Speed switching
- Suffix "-Q1" for AEC-Q101

Application

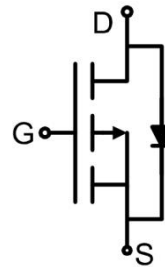
- Battery protection
- Load switch
- Power management

Package

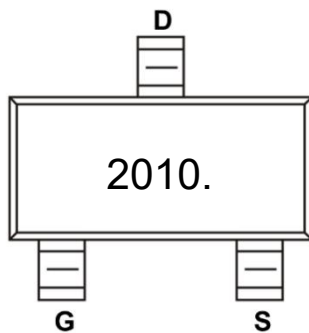


SOT-23-3L

Circuit diagram



Marking



Absolute maximum ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 10	V
Continuous Drain Current($T_c=25^{\circ}\text{C}$)	I_D	-10	A
Continuous Drain Current($T_c=70^{\circ}\text{C}$)	$I_D(70^{\circ}\text{C})$	-8	A
Pulsed Drain Current ¹⁾	I_{DM}	-32	A
Power Dissipation	P_D	2.5	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	50	$^{\circ}\text{C}/\text{W}$
Junction Temperature	T_J	150	$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	-55 ~ +150	$^{\circ}\text{C}$

Electrical characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$	-20			V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -20\text{V}, V_{GS} = 0\text{V}, T_c = 25^{\circ}\text{C}$			-1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 10\text{V}, V_{DS} = 0\text{V}$			± 100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-0.4	-0.62	-1.0	V
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = -4.5\text{V}, I_D = -6\text{A}$		15	23	m Ω
		$V_{GS} = -2.5\text{V}, I_D = -6\text{A}$		18	26	
		$V_{GS} = -1.8\text{V}, I_D = -4\text{A}$		24	34	
Dynamic characteristics²⁾						
Input Capacitance	C_{iss}	$V_{DS} = -10\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		2992		pF
Output Capacitance	C_{oss}			330		
Reverse Transfer Capacitance	C_{rss}			272		
Total Gate Charge	Q_g	$V_{DS} = -15\text{V}, V_{GS} = -10\text{V}, I_D = -9.1\text{A}$		72.8		nC
Gate-Source Charge	Q_{gs}			6.6		
Gate-Drain Charge	Q_{gd}			10.1		
Turn-on delay time	$t_{d(on)}$	$V_{DS} = -15\text{V}, V_{GS} = -10\text{V}, I_D = -6\text{A}, R_{GEN} = 2.5\Omega$		7		nS
Turn-on rise time	t_r			33		
Turn-off delay time	$t_{d(off)}$			130		
Turn-off fall time	t_f			132		
Source-Drain Diode characteristics						
Diode Forward Current	I_S				-10	A
Diode Forward Voltage	V_{SD}	$V_{GS} = 0\text{V}, I_S = -10\text{A}$			-1.2	V
Reverse Recovery Charge	Q_{rr}	$I_F = -6\text{A}, di/dt = 100\text{A}/\mu\text{s}$		34		nC
Reverse Recovery Time	t_{rr}			67		nS

Notes:

- 1) Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$.
- 2) Guaranteed by design, not subject to production.

Typical Characteristics

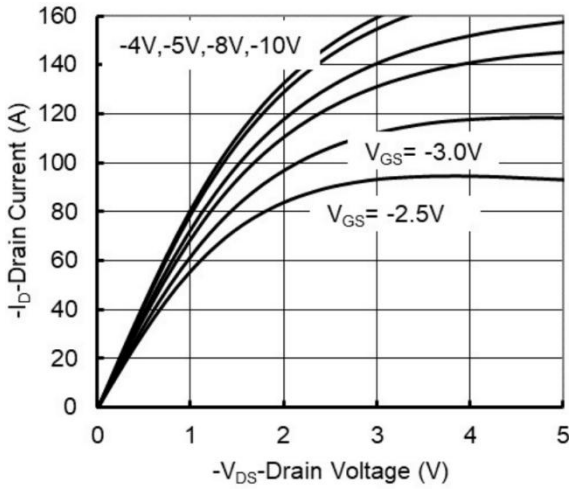


Figure 1. Output Characteristics

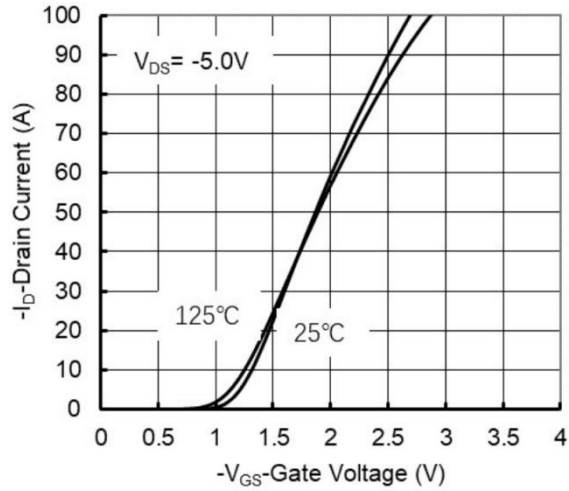


Figure 2. Transfer Characteristics

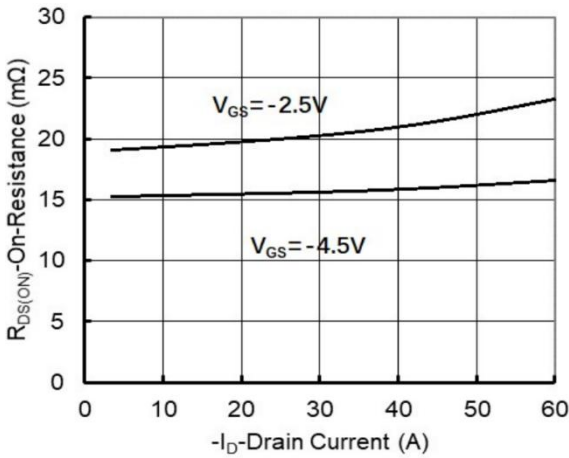


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

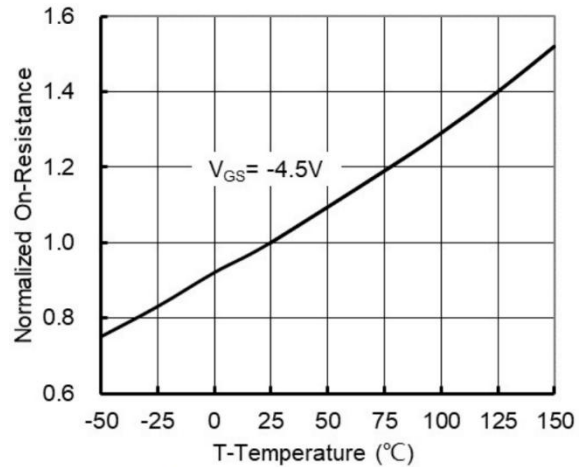


Figure 4. On-Resistance vs. Junction Temperature

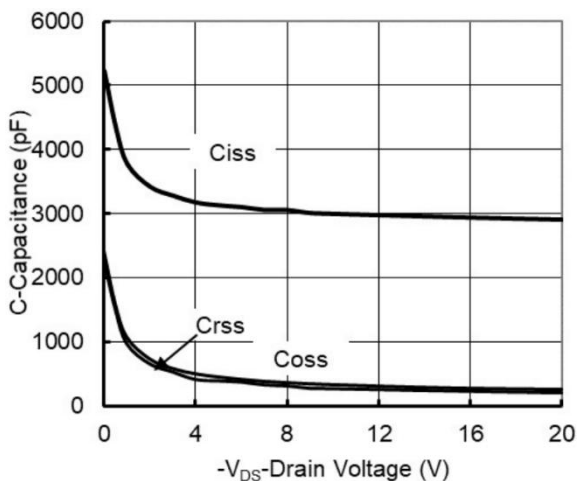


Figure 5. Capacitance Characteristics

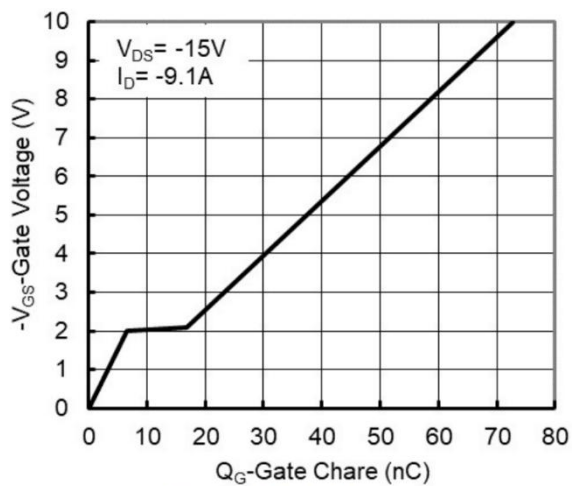


Figure 6. Gate Charge

Typical Characteristics

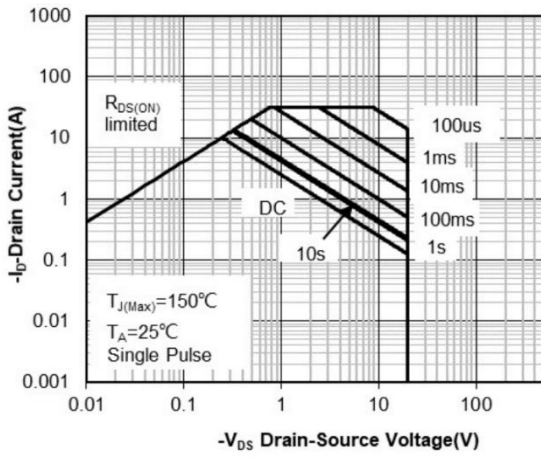


Figure 7. Safe Operation Area

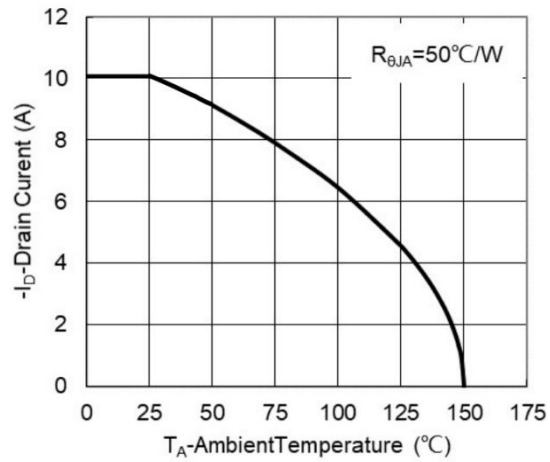
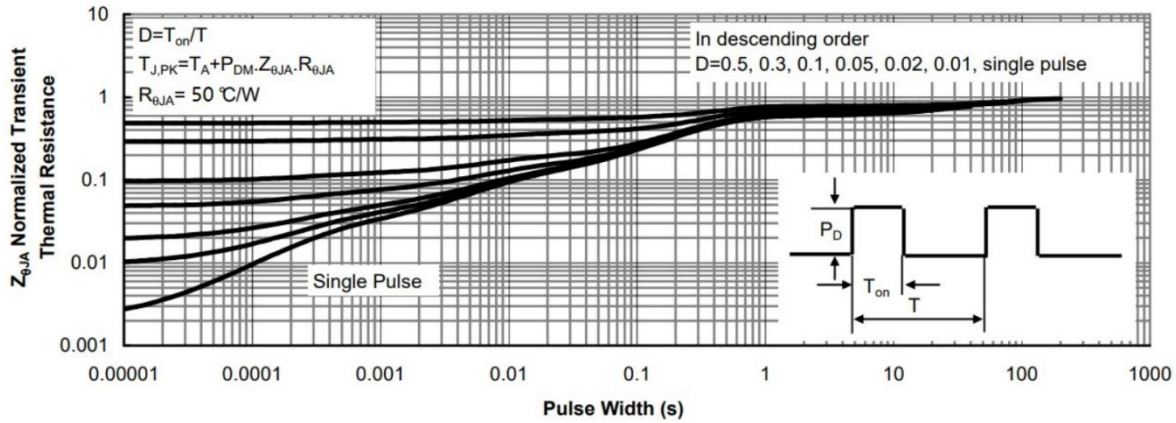
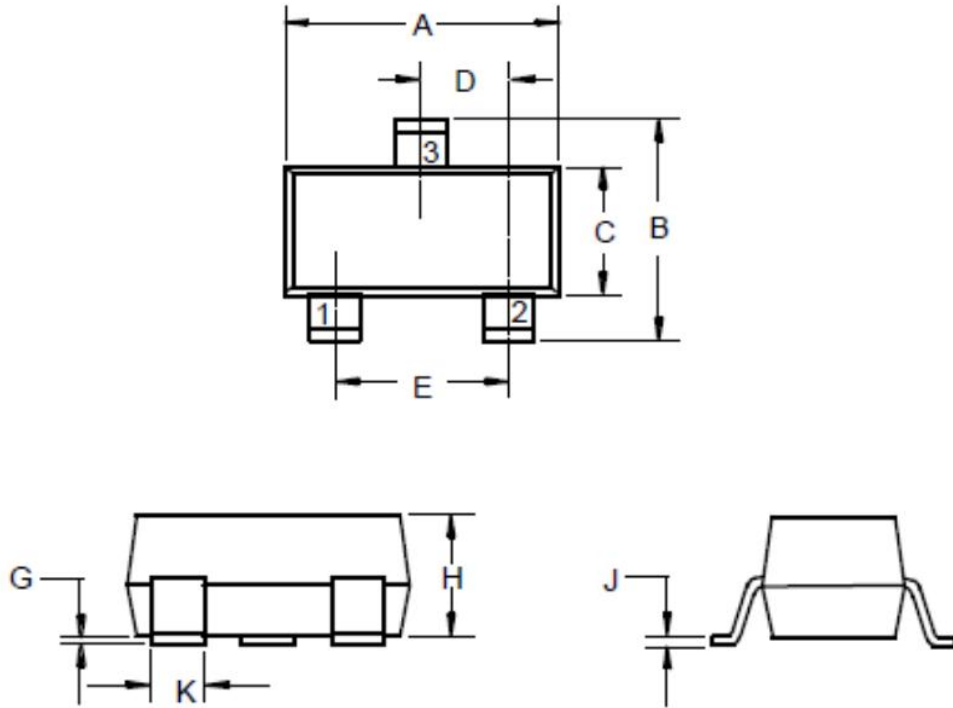


Figure 8. Maximum Continuous Drain Current vs Case Temperature



SOT-23-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.820	3.020	0.111	0.119
B	2.650	2.950	0.104	0.116
C	1.500	1.700	0.059	0.067
D	0.950 TYP		0.037 TYP	
E	1.800	2.000	0.071	0.079
G	0.000	0.200	0.000	0.008
H	1.050	1.250	0.041	0.049
J	0.100	0.200	0.004	0.008
K	0.300	0.500	0.012	0.020